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Client Matter No. 81848.0016.001

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 09/546,174	Confirmation No.: 4793
Application of: Chih-Chien Liu, Ta-Shan Tseng, W. B. Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun	Customer No.: 25235
Filed: April 11, 2000	
Art Unit: 1711	
Examiner: Sergent, Rabon A.	
Attorney Docket No. UMC-96-279 CON	
For: HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS	

AMENDMENT AND RESPONSE PURSUANT TO FINAL OFFICE ACTION
DATED AUGUST 25, 2005

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the final office communication mailed August 25, 2005, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 11 of this paper.